



1733

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Edward A. Schrock et al.

Title: METHOD FOR ATTACHING A SEMICONDUCTOR DIE TO A SUBSTRATE

Docket No.: 303.527US2

Serial No.: 09/649,827

Filed: August 29, 2000

Due Date: October 17, 2001

Examiner: John J. Gallagher

Group Art Unit: 1733

Commissioner for Patents
Washington, D.C. 20231

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We are transmitting herewith the following attached items (as indicated with an "X"):

- ☒ A return postcard.
- ☒ An Amendment and Response under 37 CFR 1.111 (10 Pages).
- ☐ Clean Version of Pending Claims (6 pgs).

Please consider this a PETITION FOR EXTENSION OF TIME for sufficient number of months to enter these papers and please charge any additional required fees or credit overpayment to Deposit Account No. 19-0743.

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CERTIFICATE UNDER 37 CFR 1.8: The undersigned hereby certifies that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail, in an envelope addressed to: Commissioner for Patents, Washington, D.C. 20231, on this 17th day of October, 2001.

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S/N 09/649,827

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PATENT

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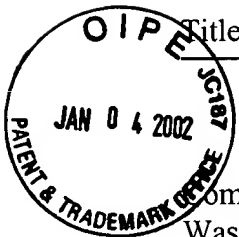
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Title: METHOD FOR ATTACHING A SEMICONDUCTOR DIE TO A SUBSTRATE



AMENDMENT AND RESPONSE UNDER 37 CFR § 1.111

Commissioner for Patents
Washington, D.C. 20231

Applicant has reviewed the Office Action mailed on July 17, 2001. Please amend the above-identified patent application as follows.

IN THE CLAIMS

Please substitute the claim set in the appendix entitled Clean Version of Pending Claims for the previously pending claim set. The substitute claim set is intended to reflect amendment of previously pending claims 39, 44, and 63. The specific amendments to individual claims are detailed in the following marked up set of claims.

39.) (Twice Amended) A method of attaching a semiconductor die to an organic support structure, comprising:

affixing a first side of a two-sided adhesive tape to a surface of the organic support structure, wherein [the] adhesive of the adhesive tape comprises a pressure sensitive, thermosetting adhesive;

elevating the temperature to 100 degrees C to activate the first side of the adhesive tape; applying pressure to the tape and organic support structure to laminate the adhesive tape to the organic support structure;

affixing a face of the semiconductor die to a second side of the adhesive tape;

elevating the temperature of the tape to activate the second side of the adhesive tape; and

applying pressure to the die and organic support structure to laminate the adhesive tape to the die.

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